

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



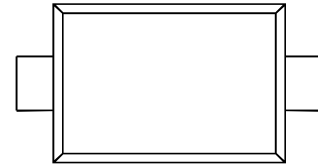
GDT



PLED

Product data sheet

- ◇ Low current rectification
- ◇ Low forward voltage
- ◇ SOD-923 Micro SMD package( Fig-1) Dimensions:  
1.0 mm x 0.6 mm (0.039" x 0.024")
- ◇ RoHS compliant
- ◇ UL-94 V-0 / Green EMC
- ◇ Matte Tin Lead finish (Pb-Free)
- ◇ Cathode Band / Device marking:



SOD-923

**Absolute Maximum Ratings** (Ta = 25 °C)

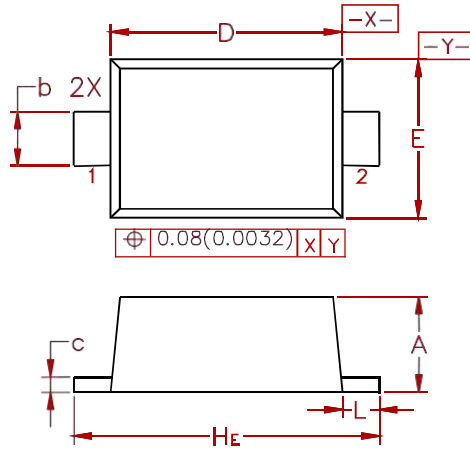
Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	30	V
V <sub>R</sub>	Reverse Voltage	30	V
I <sub>O</sub>	Continuous Forward Current	100	mA
I <sub>FSM</sub>	Non-Repetitive Peak Forward Current *1	500	mA
T <sub>J</sub>	Junction Temperature	125	°C
T <sub>STG</sub>	Storage Temperature	-55 to +125	°C

\*1: 8.3ms Single Half Sine-Wave

**Electrical Characteristics** (Ta = 25 °C)

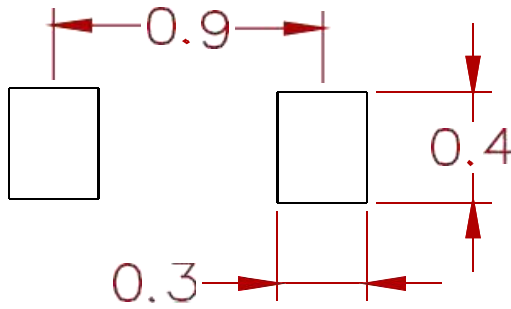
Symbol	Parameter	Conditions	Min	TYP	Max	Units
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 10mA			0.35	V
		I <sub>F</sub> = 20mA			0.40	V
BV <sub>R</sub>	Breakdown Voltage	I <sub>R</sub> = 100 μ A	30			V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 10V			10	μ A
		V <sub>R</sub> = 30V			50	μ A

**PACKAGE MECHANICAL DATA**



Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.36	0.40	0.43	0.014	0.016	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

**Suggested Pad Layout**



Dimensions: Millimeters

**REEL SPECIFICATION**

P/N	PKG	QTY
CDB0130QRM-MS	SOD-923	8000

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